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Appl. No. 10/699,130
Amdt. Dated August 16, 2007
Reply to Office Action of May 16, 2007

Amendments to the Claims:

This listing will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-8 (Canceled)

Claim 9 (Previously presented): A method of fabricating a molded form used to enclose and protect an electrical assembly provided on a printed circuit board which method comprises:

providing a printed circuit board having an electrical assembly formed thereon and having an upper surface and a lower surface, the upper surface of the printed circuit board having a topography defined by the size, shape and location of individual components of the electrical assembly;

producing an electronic image of the upper surface;

modifying the electronic image of the upper surface by measuring the heights of the individual components of the electrical assembly and either adding a factor to the measured heights or subtracting a factor from the measured heights;

fabricating a mold for injection molding a molded form that is substantially complementarily shaped to the topography of the upper surface of the printed circuit board, said

Appl. No. 10/699,130
Amdt. Dated August 16, 2007
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mold being complementarily shaped to the topography of the upper surface of the printed circuit board by an operation that utilizes the modified electronic image of the upper surface of the printed circuit board, said mold including protrusions that are complementarily shaped to individual ones of the components of the electrical assembly; and

injection molding a molded form using the mold which molded form is configured to enclose and protect an electrical assembly provided on a printed circuit board, the molded form having recesses formed by the protrusions, which recesses are complementarily shaped to individual ones of the components of the electrical assembly and configured to receive individual ones of the components of the electrical assembly.

Claim 10 (Canceled)

Claim 11 (Canceled)

Claim 12 (Original): A method of fabricating a molded form used to protect an electrical assembly provided on a printed circuit board according to claim 9, wherein the electronic image is modified by adjusting for space around each of the individual components of the electrical assembly.

Claim 13 (Original): A method of fabricating a molded form used to protect an electrical

Appl. No. 10/699,130
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assembly provided on a printed circuit board according to claim 9, wherein the molded form is co-molded.

Claim 14 (Original): A method of fabricating a molded form used to protect an electrical assembly provided on a printed circuit board according to claim 13, wherein the co-molded form comprises a outer surface layer that is harder than a central portion of the co-molded form.

Claim 15 (Previously presented): A method of fabricating a molded form used to protect an electrical assembly provided on a printed circuit board according to claim 14, wherein the outer surface layer has ridges formed therein.

Claim 16 (Original): A method of fabricating a molded form used to protect an electrical assembly provided on a printed circuit board according to claim 9, wherein the molded form comprises upper and lower molded form portions.

Claim 17 (Original): A method of fabricating a molded form used to protect an electrical assembly provided on a printed circuit board according to claim 16, wherein the upper and lower molded form portions are coupled together by a hinge.

Claim 18 (Original): A method of fabricating a molded form used to protect an electrical

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assembly provided on a printed circuit board according to claim 9, wherein an embedded structure is molded into the molded form.

Claim 19 (Original): A method of fabricating a molded form used to protect an electrical assembly provided on a printed circuit board according to claim 18, wherein the embedded structure comprises at least one of a rigid structure, an emi shield and a thermal conductor.

Claim 20 (Original): A method of fabricating a molded form used to protect an electrical assembly provided on a printed circuit board according to claim 9, wherein the electrical assembly comprises an assembly that is used in down hole applications.

Claim 21 (Canceled)

Claims 22-23 (Canceled)